WHAT IS CLAIMED IS:

1. A method of mounting an electronic component on a substrate, comprising:

placing the electronic component on the substrate with a solid support interposed between the electronic component and the substrate so as to space a terminal conductor of the electronic component from a corresponding terminal pad on the substrate;

melting a conductive bonding material on the terminal pad; and thereafter

melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the conductive bonding material melting on the corresponding terminal pad.

2. The method according to claim 1, wherein said solid support is made of a thermoplastic resin material having a melting point higher than that of the conductive bonding material.

3. The method according to claim 1, wherein said conductive bonding material comprises solder particles dispersed in a flux including an organic solvent.

4. The method according to claim 1, wherein said solid support has an adherent property on its surface.

5. A method of mounting an electronic component on a substrate, comprising:

melting a conductive bonding material on a terminal pad on the substrate under a high temperature atmosphere; and

contacting a terminal conductor of the electronic component on the conductive bonding material on the terminal pad continuously under the high temperature atmosphere.

6. The method according to claim 5, further comprising:

placing the electronic component on the substrate, prior to melting of the conductive bonding material, with a solid support interposed between the electronic component and the substrate so as to space the terminal conductor from the terminal pad; and

melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the conductive bonding material on the corresponding terminal pad, when the terminal conductor is contacted on the terminal pad.

7. The method according to claim 6, wherein said solid support is made of a thermoplastic resin material having a melting point higher than that of the conductive bonding material.

8. The method according to claim 7, wherein said solid support has an adherent property on its surface.

9. The method according to claim 5, wherein said conductive bonding material comprises solder particles dispersed in a flux including an organic solvent.

10. A method of mounting an electronic component on a substrate, comprising:

melting a solder paste on a terminal pad on the substrate;

and

placing a terminal conductor of the electronic component on the solder paste on the terminal pad, said solder paste being kept melted.

11. The method according to claim 10, further comprising:

setting the electronic component on the substrate, prior to melting of the solder paste, with a solid support interposed between the electronic component and the substrate so as to space the terminal conductor from the terminal pad; and

melting the solid support so as to move down the electronic component toward the substrate, thereby contacting the terminal conductor with the solder paste on the corresponding terminal pad, said solder paste being kept melted.

12. The method according to claim 11, wherein said solid support is made of a thermoplastic resin material having a melting point higher than that of the solder paste.

13. The method according to claim 12, wherein said solid support has an adherent property on its surface.

14. An electronic circuit board comprising:

a substrate;

an electronic component mounted on a surface of the substrate and having a terminal conductor received on a terminal pad on the substrate; and

a thermoplastic resin material interposed between the substrate and the electronic component.

15. The electronic circuit board according to claim 14, wherein said thermoplastic resin material has a higher heat conductivity.

16. An electronic component unit comprising:

a terminal conductor of a predetermined height standing on a surface opposed to a substrate; and

a solid support standing on the surface, said solid support having a height larger than the predetermined height.

17. The electronic component unit according to claim 16, wherein said solid support is made of a thermoplastic resin material.

18. The electronic component unit according to claim 16, wherein said solid support has an adherent property on its surface.

19. The electronic component unit according to claim 16, wherein said thermoplastic resin material has a higher heat conductivity.